

HSEC8-160-01-S-DV-A

# 0,80mm HI-SPEED SOCKET HSEC8 SERIES

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HSEC8-DV](http://www.samtec.com?HSEC8-DV)

### Insulator Material:

Black Liquid Crystal Polymer



### Contact:

BeCu  
Plating:  
Au or Sn over 50µ" (1,27µm) Ni



### Current Rating:

3.1A @ 30°C Temperature Rise

### Operating Temp:

-55°C to +125°C

### Card Insertion Depth:

(3,15mm) .125" nominal

### RoHS Compliant:

Yes

### Processing:

#### Max Processing Temp:

230°C for 60 seconds, or 260°C for 20 seconds

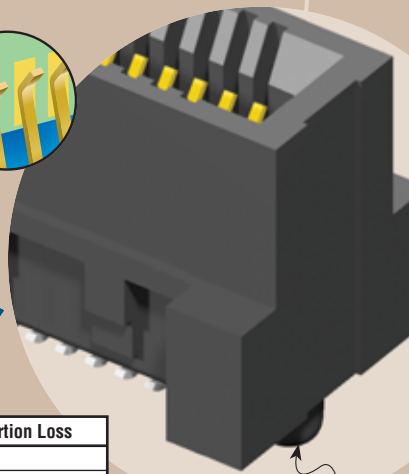
#### Lead-Free Solderable:

Yes

#### SMT Lead Coplanarity:

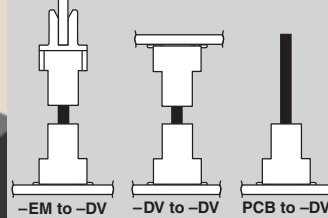
(0,10mm) .004" max (10-60)

Mates with:  
1,6mm thick cards,  
EEDP, HSC8, HSF8

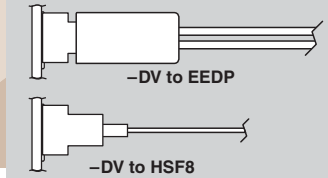


Alignment Pins

## BOARD-TO-BOARD APPLICATIONS



## HIGH SPEED CABLE & FLEX APPLICATIONS

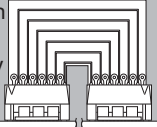


|                             |                             |
|-----------------------------|-----------------------------|
| 0,80mm HSEC8                | Rated @ -3dB Insertion Loss |
| 7,98mm Stack Height         |                             |
| Single-Ended Signaling      | 8 GHz / 16 Gbps             |
| Differential Pair Signaling | 10.5 GHz / 21 Gbps          |

For complete test data go to [www.samtec.com?HSEC8](http://www.samtec.com?HSEC8) or contact [sig@samtec.com](mailto:sig@samtec.com)

## STANDARD & CUSTOM CARDS AVAILABLE

- Standard high speed interface cards for 19mm, 25mm & 30mm mated heights, single-ended & differential applications. See HSC8 Series.
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes



## APPLICATION SPECIFIC OPTION



Note: Other Gold plating options available. Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

## HSEC8 - 1 POSITIONS PER ROW - CARD THICKNESS - PLATING OPTION - DV - A - OTHER OPTION

10, 13, 20, 25, 30, 37, 40, 49, 50, 60

-01 = (1,60mm) .062" thick card

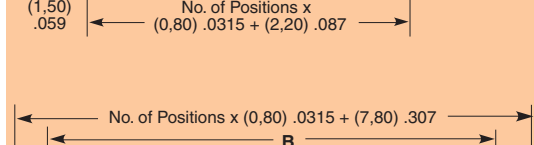
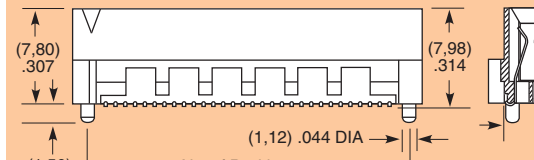
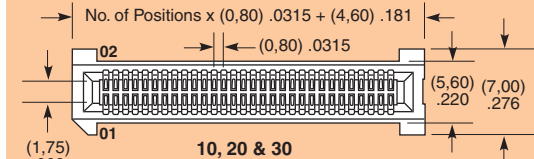
-S = 30µ" (0,76µm) Gold on contact, Matte Tin on tail

-K = (5,50mm) .217" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel Packaging

-L = Latching Option (For use with EEDP.) (13, 25, 37, 49 only)

-BL = Board Locks (40, 50, 60 only)



| POSITIONS PER ROW | A             | B             |
|-------------------|---------------|---------------|
| 13*               | (6,10) .240   | (15,00) .591  |
| 25*               | (6,10) .240   | (24,60) .969  |
| 37*               | (18,10) .713  | (34,20) 1.346 |
| 40                | (18,90) .744  | (36,60) 1.441 |
| 49*               | (22,90) .902  | (43,80) 1.724 |
| 50                | (22,90) .902  | (44,60) 1.756 |
| 60                | (26,90) 1.059 | (52,60) 2.071 |

Positions where no dimensions are given do not have keying feature.  
\*Mates with EEDP Series.

| CONNECTOR | CABLE*  |
|-----------|---------|
| HSEC8-113 | EEDP-08 |
| HSEC8-125 | EEDP-16 |
| HSEC8-137 | EEDP-24 |
| HSEC8-149 | EEDP-32 |

Due to technical progress, all designs, specifications and components are subject to change without notice.

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